



G&P TECHNOLOGY

POLI-610 Polishing Tool



Your source for leading-edge surface processing solutions



The G&P Technology POLI-610 Polishing tool is used for the precision surface preparation of very hard, brittle materials such as Silicon Carbide, Gallium Nitride, and Sapphire. This is an especially good polishing tool for such LED materials which require relatively long polishing cycles and significant application of down force to achieve the desired removal rate and surface quality. The POLI-610 polishing tool is an excellent choice for economical processing of 3" (76mm) and 4" (100mm) wafers using "batch" style processing. In the tradition of all G & P Technology tools and equipment, the POLI-610 is a versatile and flexible process tool already chosen by R&D laboratories, university research centers, consumables suppliers, substrate manufacturers, and developers of LED substrates, and III-V materials.

FEATURES

- Rigid and stable design for long life and peak performance in polishing applications used for processing very hard, brittle materials
- Size designed for R&D laboratories but capable for pre-production and production-level manufacturing making process development and technology transfer more efficient and cost-effective
- Affordable in-house polishing capability with state-of-the-art components
- Includes many important features and benefits of larger, more expensive machines in an economical and space saving unit conditioning disk
- Easy to learn, easy to operate, and easy to maintain





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CONDITIONING ARM OPTIONS

Oscillating Arm Conditioning (linear sweep - optional for single carrier systems)

- 195mm end effector, segmented or pellet
- Downforce range, 5 - 20 kgf (11 - 44 lbf)
- Sweep rate, 0 - 12 sweep/minute



STANDARD CONFIGURATION - Model POLI-610		
Wafer size capacity	3" wafers	Max of 8/cycle
	4" wafers	Max of 6/cycle
Typical application	SiC, GaN, Sapphire, etc.	
1 polishing platen	Hard Anodized Aluminum	
	Diameter	623mm 24.5"
	Speed range	30 - 200 rpm
Number of wafer carriers	1 or 2 (without conditioner system)	
	Speed range	30 - 200 rpm
	Standard type	Ceramic; back referencing
	Oscillation range	±12mm ±0.5"
Pad conditioner	optional on single carrier style	
Slurry pumps	3	
Operator interface	Intuitive touch screen	
Loading system	Manual load/unload	

OPTIONS AVAILABLE	
Second wafer carrier	N/A with pad conditioning
Pad conditioner system	N/A in 2-spindle/carrier model
	Type Oscillation style
	Feature 8-zone conditioning control
Pad profiling system	To control pad shape
Low pressure polishing system	N/A on POLI-610
End point systems	Frictional force
	Temperature
Table rinse spray	High pressure spray system
Platen temperature control	Customer provides chiller
Teflon coated polishing table	Optional

DIMENSIONS			FACILITIES	
Metric	1200W x 1290D x 1960H		Power	220VAC, 3 PH, 30A
Inches	47.5W x 51D x 77H		DI Water	2 l/min avg, 10 l/min peak
Weight	~1400 kg	3087 lbs	CDA	5 SCFM
			Exhaust	100 CFM



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